

PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	MMS/15/9469	
1.3 Title of PCI	IMPROVED PACKING for all EEPROM in WLCSP	
1.4 Product Category	All EEPROM in WLCSP	
1.5 Issue date	2015-10-28	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	SETTLES JEFF
2.1.2 Phone	+44 1628896222
2.1.3 Email	jeff.settles@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Benoit RODRIGUES
2.1.2 Marketing Manager	Hubert LEDUC
2.1.3 Quality Manager	Rita PAVANO

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Materials	New Indirect material part number (same supplier or different supplier): Boxes, trays, carriers, back grinding tape, wafer mounting tape, mold tape, ...	STATSChipPAC subcontractor

4. Description of change

	Old	New
4.1 Description	No bubble sheet, no MBB, no desiccant, no humidity indicator, no EPE foam	Adding bubble wrap sheets, Moisture barrier bag, desiccant and humidity indicator, EPE protector foam
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on form by adding the material of the improved packing	

5. Reason / motivation for change

5.1 Motivation	Will improve resistance to mechanical and environmental stresses during transportation
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	N/A
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7. Timing / schedule

7.1 Date of qualification results	2015-10-22
7.2 Intended start of delivery	2015-10-26
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

9469PpPrdtLst.pdf
PCI NEW PACKING all WLCSP.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	M24M02-DRCS6TP/K	

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